

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Washington, D.C. 20231 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO. MTI-31607	Serial No. 10/050,507
	Applicant Lee, Teck Kheng	Confirmation No. 7687
	Filing Date January 16, 2002	Group Art Unit 2813

U.S. PATENT DOCUMENTS

Examiner Initials		Patent/Publication Number	Publication Date	Patentee or Applicant	U.S. Class	Sub-Class
<i>[Signature]</i>	A1	6,281,046 B1	08/28/01	Lam	438	113
	A2	6,239,496 B1	05/29/01	Asada	257	777
	A3	6,180,881 B1	01/30/01	Isaak	174	52.4
	A4	5,844,315	12/01/98	Melton et al.	257	738
	A5	5,608,265	03/04/97	Kitano et al.	257	738
<i>[Signature]</i>	A6	4,954,875	09/04/90	Clements	357	75

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initials	Non-Patent Document
<i>[Signature]</i>	Australian Search Report dated 03 November 2004 (5 pages).

Examiner Initials	<i>[Signature]</i>	Date Considered	2/2/05
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention


Elimination of RDL Using Tape Base Flip Chip on Flex for Die
Stacking

Application Number : 10/050507
Confirmation Number: 7687
First Named Applicant: Teck Lee
Attorney Docket Number: MTI-31607
Art Unit: 2813
Examiner: Jack SJ Chen
Search string: (6308525 or 5468995 or 6610559).pn



US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6308525	2001-03-27	Imasu et al.		361	783
	2	5468995	1995-11-21	Higgins III		257	697
	3	6610559	2003-08-26	Wang et al.		438	108

Signature

Examiner Name	Date
	2/2/06

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

**Title of
Invention**



Elimination of RDk Using Tape Base Flip Chip on Flex for Die
Stacking

Application Number : 10/050507
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Art Unit: 2813
Examiner: Jack SJ Chen
Search string: (4415403 or 6847105).pn



US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4415403	1983-11-15	Bakewell		216	27
	2	6847105	2005-01-25	Koopmans		257	686

Signature

	Examiner Name		Date
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Examiner: Jack SJ Chen
Search string: (6624060 or 20020027080 or 20030134450).pn



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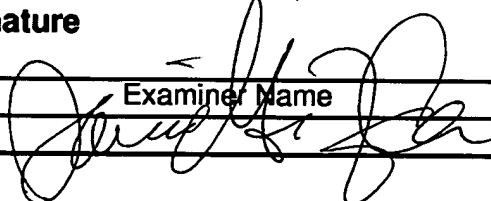
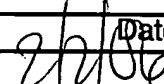
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6624060	2003-09-23	Chen et al.		438	613

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020027080	2002-03-07	Yoshioka et al.	A1	205	123
	2	20030134450	2003-07-17	Lee	A1	438	106

Signature

	Examiner Name		Date
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